

74AUP3G04

Low-power triple inverter

Rev. 7 — 29 January 2013

Product data sheet

1. General description

The 74AUP3G04 provides a low-power, low-voltage triple inverting buffer.

Schmitt trigger action at all inputs makes the circuit tolerant of slower input rise and fall times across the entire V_{CC} range from 0.8 V to 3.6 V.

This device ensures a very low static and dynamic power consumption across the entire V_{CC} range from 0.8 V to 3.6 V.

This device is fully specified for partial Power-down applications using I_{OFF} . The I_{OFF} circuitry disables the output, preventing a damaging backflow current through the device when it is powered down.

2. Features and benefits

- Wide supply voltage range from 0.8 V to 3.6 V
- High noise immunity
- Complies with JEDEC standards:
 - ◆ JESD8-12 (0.8 V to 1.3 V)
 - ◆ JESD8-11 (0.9 V to 1.65 V)
 - ◆ JESD8-7 (1.2 V to 1.95 V)
 - ◆ JESD8-5 (1.8 V to 2.7 V)
 - ◆ JESD8-B (2.7 V to 3.6 V)
- ESD protection:
 - ◆ HBM JESD22-A114F Class 3A exceeds 5000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
 - ◆ CDM JESD22-C101E exceeds 1000 V
- Low static power consumption; $I_{CC} = 0.9 \mu A$ (maximum)
- Latch-up performance exceeds 100 mA per JESD 78B Class II
- Inputs accept voltages up to 3.6 V
- Low noise overshoot and undershoot < 10 % of V_{CC}
- I_{OFF} circuitry provides partial Power-down mode operation
- Multiple package options
- Specified from $-40^{\circ}C$ to $+85^{\circ}C$ and $-40^{\circ}C$ to $+125^{\circ}C$



3. Ordering information

Table 1. Ordering information

Type number	Package				Version
	Temperature range	Name	Description		
74AUP3G04DC	–40 °C to +125 °C	VSSOP8	plastic very thin shrink small outline package; 8 leads; body width 2.3 mm		SOT765-1
74AUP3G04GT	–40 °C to +125 °C	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 1 × 1.95 × 0.5 mm		SOT833-1
74AUP3G04GF	–40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.35 × 1 × 0.5 mm		SOT1089
74AUP3G04GD	–40 °C to +125 °C	XSON8	plastic extremely thin small outline package; no leads; 8 terminals; body 3 × 2 × 0.5 mm		SOT996-2
74AUP3G04GM	–40 °C to +125 °C	XQFN8	plastic, extremely thin quad flat package; no leads; 8 terminals; body 1.6 × 1.6 × 0.5 mm		SOT902-2
74AUP3G04GN	–40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.2 × 1.0 × 0.35 mm		SOT1116
74AUP3G04GS	–40 °C to +125 °C	XSON8	extremely thin small outline package; no leads; 8 terminals; body 1.35 × 1.0 × 0.35 mm		SOT1203

4. Marking

Table 2. Marking codes

Type number	Marking code ^[1]
74AUP3G04DC	p04
74AUP3G04GT	p04
74AUP3G04GF	p4
74AUP3G04GD	p04
74AUP3G04GM	p04
74AUP3G04GN	p4
74AUP3G04GS	p4

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

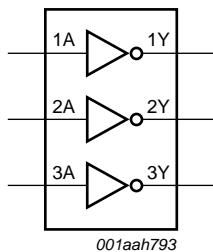


Fig 1. Logic symbol

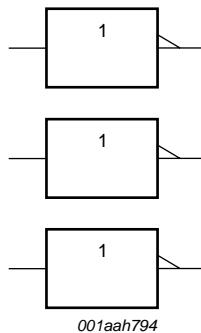


Fig 2. IEC logic symbol

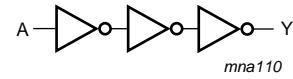


Fig 3. Logic diagram (one gate)

6. Pinning information

6.1 Pinning

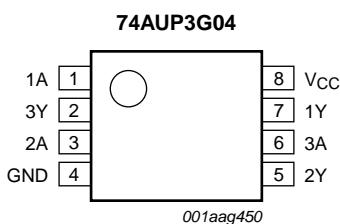


Fig 4. Pin configuration SOT765-1

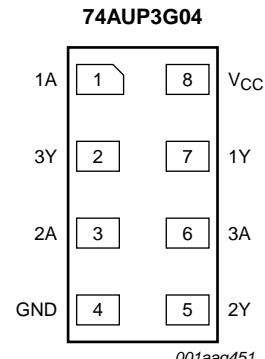
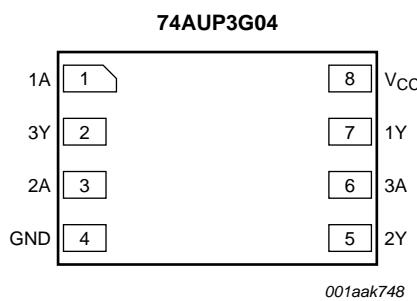
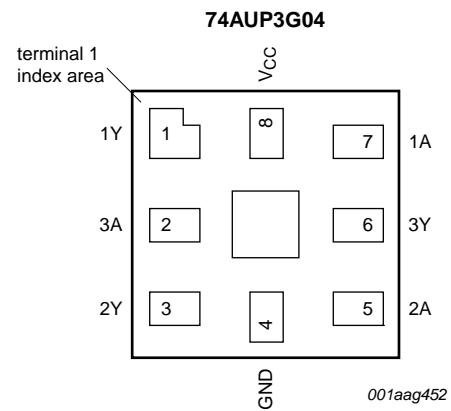


Fig 5. Pin configuration SOT833-1, SOT1089, SOT1116 and SOT1203



Transparent top view

Fig 6. Pin configuration SOT996-2



Transparent top view

Fig 7. Pin configuration SOT902-2

6.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
	SOT765-1, SOT833-1, SOT1089, SOT996-2, SOT1116 and SOT1203	SOT902-2
1A, 2A, 3A	1, 3, 6	7, 5, 2
1Y, 2Y, 3Y	7, 5, 2	1, 3, 6
GND	4	4
V _{CC}	8	8

7. Functional description

Table 4. Function table^[1]

Input	Output
nA	nY
L	H
H	L

[1] H = HIGH voltage level; L = LOW voltage level.

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+4.6	V
I_{IK}	input clamping current	$V_I < 0 \text{ V}$	-50	-	mA
V_I	input voltage		[1] -0.5	+4.6	V
I_{OK}	output clamping current	$V_O < 0 \text{ V}$	-50	-	mA
V_O	output voltage	Active mode and Power-down mode	[1] -0.5	+4.6	V
I_O	output current	$V_O = 0 \text{ V}$ to V_{CC}	-	± 20	mA
I_{CC}	supply current		-	50	mA
I_{GND}	ground current		-50	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40 \text{ }^{\circ}\text{C}$ to $+125 \text{ }^{\circ}\text{C}$	[2] -	250	mW

[1] The minimum input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For VSSOP8 packages: above 110 °C the value of P_{tot} derates linearly with 8.0 mW/K.

For XSON8 and XQFN8 packages: above 118 °C the value of P_{tot} derates linearly with 7.8 mW/K.

9. Recommended operating conditions

Table 6. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		0.8	3.6	V
V_I	input voltage		0	3.6	V
V_O	output voltage	Active mode	0	V_{CC}	V
		Power-down mode; $V_{CC} = 0 \text{ V}$	0	3.6	V
T_{amb}	ambient temperature		-40	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 0.8 \text{ V}$ to 3.6 V	-	200	ns/V

10. Static characteristics

Table 7. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{\text{amb}} = 25^{\circ}\text{C}$						
V_{IH}	HIGH-level input voltage	$V_{\text{CC}} = 0.8 \text{ V}$	0.70 V_{CC}	-	-	V
		$V_{\text{CC}} = 0.9 \text{ V to } 1.95 \text{ V}$	0.65 V_{CC}	-	-	V
		$V_{\text{CC}} = 2.3 \text{ V to } 2.7 \text{ V}$	1.6	-	-	V
		$V_{\text{CC}} = 3.0 \text{ V to } 3.6 \text{ V}$	2.0	-	-	V
V_{IL}	LOW-level input voltage	$V_{\text{CC}} = 0.8 \text{ V}$	-	-	0.30 V_{CC}	V
		$V_{\text{CC}} = 0.9 \text{ V to } 1.95 \text{ V}$	-	-	0.35 V_{CC}	V
		$V_{\text{CC}} = 2.3 \text{ V to } 2.7 \text{ V}$	-	-	0.7	V
		$V_{\text{CC}} = 3.0 \text{ V to } 3.6 \text{ V}$	-	-	0.9	V
V_{OH}	HIGH-level output voltage	$V_{\text{I}} = V_{\text{IH}}$ or V_{IL}				
		$I_{\text{O}} = -20 \mu\text{A}; V_{\text{CC}} = 0.8 \text{ V to } 3.6 \text{ V}$	$V_{\text{CC}} - 0.1$	-	-	V
		$I_{\text{O}} = -1.1 \text{ mA}; V_{\text{CC}} = 1.1 \text{ V}$	0.75 V_{CC}	-	-	V
		$I_{\text{O}} = -1.7 \text{ mA}; V_{\text{CC}} = 1.4 \text{ V}$	1.11	-	-	V
		$I_{\text{O}} = -1.9 \text{ mA}; V_{\text{CC}} = 1.65 \text{ V}$	1.32	-	-	V
		$I_{\text{O}} = -2.3 \text{ mA}; V_{\text{CC}} = 2.3 \text{ V}$	2.05	-	-	V
		$I_{\text{O}} = -3.1 \text{ mA}; V_{\text{CC}} = 2.3 \text{ V}$	1.9	-	-	V
		$I_{\text{O}} = -2.7 \text{ mA}; V_{\text{CC}} = 3.0 \text{ V}$	2.72	-	-	V
		$I_{\text{O}} = -4.0 \text{ mA}; V_{\text{CC}} = 3.0 \text{ V}$	2.6	-	-	V
V_{OL}	LOW-level output voltage	$V_{\text{I}} = V_{\text{IH}}$ or V_{IL}				
		$I_{\text{O}} = 20 \mu\text{A}; V_{\text{CC}} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.1	V
		$I_{\text{O}} = 1.1 \text{ mA}; V_{\text{CC}} = 1.1 \text{ V}$	-	-	0.3 V_{CC}	V
		$I_{\text{O}} = 1.7 \text{ mA}; V_{\text{CC}} = 1.4 \text{ V}$	-	-	0.31	V
		$I_{\text{O}} = 1.9 \text{ mA}; V_{\text{CC}} = 1.65 \text{ V}$	-	-	0.31	V
		$I_{\text{O}} = 2.3 \text{ mA}; V_{\text{CC}} = 2.3 \text{ V}$	-	-	0.31	V
		$I_{\text{O}} = 3.1 \text{ mA}; V_{\text{CC}} = 2.3 \text{ V}$	-	-	0.44	V
		$I_{\text{O}} = 2.7 \text{ mA}; V_{\text{CC}} = 3.0 \text{ V}$	-	-	0.31	V
I_{I}	input leakage current	$V_{\text{I}} = \text{GND to } 3.6 \text{ V}; V_{\text{CC}} = 0 \text{ V to } 3.6 \text{ V}$	-	-	± 0.1	μA
		$V_{\text{I}} \text{ or } V_{\text{O}} = 0 \text{ V to } 3.6 \text{ V}; V_{\text{CC}} = 0 \text{ V}$	-	-	± 0.2	μA
ΔI_{OFF}	additional power-off leakage current	$V_{\text{I}} \text{ or } V_{\text{O}} = 0 \text{ V to } 3.6 \text{ V}; V_{\text{CC}} = 0 \text{ V to } 0.2 \text{ V}$	-	-	± 0.2	μA
I_{CC}	supply current	$V_{\text{I}} = \text{GND or } V_{\text{CC}}; I_{\text{O}} = 0 \text{ A}; V_{\text{CC}} = 0.8 \text{ V to } 3.6 \text{ V}$	-	-	0.5	μA
ΔI_{CC}	additional supply current	$V_{\text{I}} = V_{\text{CC}} - 0.6 \text{ V}; I_{\text{O}} = 0 \text{ A}; V_{\text{CC}} = 3.3 \text{ V}$	-	-	40	μA
C_{I}	input capacitance	$V_{\text{CC}} = 0 \text{ V to } 3.6 \text{ V}; V_{\text{I}} = \text{GND or } V_{\text{CC}}$	-	1.0	-	pF
C_{O}	output capacitance	$V_{\text{O}} = \text{GND}; V_{\text{CC}} = 0 \text{ V}$	-	1.8	-	pF

Table 7. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{\text{amb}} = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$						
V_{IH}	HIGH-level input voltage	$V_{\text{CC}} = 0.8 \text{ V}$	0.70 V_{CC}	-	-	V
		$V_{\text{CC}} = 0.9 \text{ V}$ to 1.95 V	0.65 V_{CC}	-	-	V
		$V_{\text{CC}} = 2.3 \text{ V}$ to 2.7 V	1.6	-	-	V
		$V_{\text{CC}} = 3.0 \text{ V}$ to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	$V_{\text{CC}} = 0.8 \text{ V}$	-	-	0.30 V_{CC}	V
		$V_{\text{CC}} = 0.9 \text{ V}$ to 1.95 V	-	-	0.35 V_{CC}	V
		$V_{\text{CC}} = 2.3 \text{ V}$ to 2.7 V	-	-	0.7	V
		$V_{\text{CC}} = 3.0 \text{ V}$ to 3.6 V	-	-	0.9	V
V_{OH}	HIGH-level output voltage	$V_{\text{I}} = V_{\text{IH}}$ or V_{IL}				
		$I_{\text{O}} = -20 \mu\text{A}$; $V_{\text{CC}} = 0.8 \text{ V}$ to 3.6 V	$V_{\text{CC}} - 0.1$	-	-	V
		$I_{\text{O}} = -1.1 \text{ mA}$; $V_{\text{CC}} = 1.1 \text{ V}$	0.7 V_{CC}	-	-	V
		$I_{\text{O}} = -1.7 \text{ mA}$; $V_{\text{CC}} = 1.4 \text{ V}$	1.03	-	-	V
		$I_{\text{O}} = -1.9 \text{ mA}$; $V_{\text{CC}} = 1.65 \text{ V}$	1.30	-	-	V
		$I_{\text{O}} = -2.3 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	1.97	-	-	V
		$I_{\text{O}} = -3.1 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	1.85	-	-	V
		$I_{\text{O}} = -2.7 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	2.67	-	-	V
		$I_{\text{O}} = -4.0 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	2.55	-	-	V
V_{OL}	LOW-level output voltage	$V_{\text{I}} = V_{\text{IH}}$ or V_{IL}				
		$I_{\text{O}} = 20 \mu\text{A}$; $V_{\text{CC}} = 0.8 \text{ V}$ to 3.6 V	-	-	0.1	V
		$I_{\text{O}} = 1.1 \text{ mA}$; $V_{\text{CC}} = 1.1 \text{ V}$	-	-	0.3 V_{CC}	V
		$I_{\text{O}} = 1.7 \text{ mA}$; $V_{\text{CC}} = 1.4 \text{ V}$	-	-	0.37	V
		$I_{\text{O}} = 1.9 \text{ mA}$; $V_{\text{CC}} = 1.65 \text{ V}$	-	-	0.35	V
		$I_{\text{O}} = 2.3 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	-	-	0.33	V
		$I_{\text{O}} = 3.1 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	-	-	0.45	V
		$I_{\text{O}} = 2.7 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	-	-	0.33	V
		$I_{\text{O}} = 4.0 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	-	-	0.45	V
I_{I}	input leakage current	$V_{\text{I}} = \text{GND}$ to 3.6 V ; $V_{\text{CC}} = 0 \text{ V}$ to 3.6 V	-	-	± 0.5	μA
I_{OFF}	power-off leakage current	V_{I} or $V_{\text{O}} = 0 \text{ V}$ to 3.6 V ; $V_{\text{CC}} = 0 \text{ V}$	-	-	± 0.5	μA
ΔI_{OFF}	additional power-off leakage current	V_{I} or $V_{\text{O}} = 0 \text{ V}$ to 3.6 V ; $V_{\text{CC}} = 0 \text{ V}$ to 0.2 V	-	-	± 0.6	μA
I_{CC}	supply current	$V_{\text{I}} = \text{GND}$ or V_{CC} ; $I_{\text{O}} = 0 \text{ A}$; $V_{\text{CC}} = 0.8 \text{ V}$ to 3.6 V	-	-	0.9	μA
ΔI_{CC}	additional supply current	$V_{\text{I}} = V_{\text{CC}} - 0.6 \text{ V}$; $I_{\text{O}} = 0 \text{ A}$; $V_{\text{CC}} = 3.3 \text{ V}$	-	-	50	μA

Table 7. Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$T_{\text{amb}} = -40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$						
V_{IH}	HIGH-level input voltage	$V_{\text{CC}} = 0.8 \text{ V}$	0.75 V_{CC}	-	-	V
		$V_{\text{CC}} = 0.9 \text{ V}$ to 1.95 V	0.70 V_{CC}	-	-	V
		$V_{\text{CC}} = 2.3 \text{ V}$ to 2.7 V	1.6	-	-	V
		$V_{\text{CC}} = 3.0 \text{ V}$ to 3.6 V	2.0	-	-	V
V_{IL}	LOW-level input voltage	$V_{\text{CC}} = 0.8 \text{ V}$	-	-	0.25 V_{CC}	V
		$V_{\text{CC}} = 0.9 \text{ V}$ to 1.95 V	-	-	0.30 V_{CC}	V
		$V_{\text{CC}} = 2.3 \text{ V}$ to 2.7 V	-	-	0.7	V
		$V_{\text{CC}} = 3.0 \text{ V}$ to 3.6 V	-	-	0.9	V
V_{OH}	HIGH-level output voltage	$V_{\text{I}} = V_{\text{IH}}$ or V_{IL}				
		$I_{\text{O}} = -20 \mu\text{A}$; $V_{\text{CC}} = 0.8 \text{ V}$ to 3.6 V	$V_{\text{CC}} - 0.11$	-	-	V
		$I_{\text{O}} = -1.1 \text{ mA}$; $V_{\text{CC}} = 1.1 \text{ V}$	0.6 V_{CC}	-	-	V
		$I_{\text{O}} = -1.7 \text{ mA}$; $V_{\text{CC}} = 1.4 \text{ V}$	0.93	-	-	V
		$I_{\text{O}} = -1.9 \text{ mA}$; $V_{\text{CC}} = 1.65 \text{ V}$	1.17	-	-	V
		$I_{\text{O}} = -2.3 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	1.77	-	-	V
		$I_{\text{O}} = -3.1 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	1.67	-	-	V
		$I_{\text{O}} = -2.7 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	2.40	-	-	V
		$I_{\text{O}} = -4.0 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	2.30	-	-	V
V_{OL}	LOW-level output voltage	$V_{\text{I}} = V_{\text{IH}}$ or V_{IL}				
		$I_{\text{O}} = 20 \mu\text{A}$; $V_{\text{CC}} = 0.8 \text{ V}$ to 3.6 V	-	-	0.11	V
		$I_{\text{O}} = 1.1 \text{ mA}$; $V_{\text{CC}} = 1.1 \text{ V}$	-	-	0.33 V_{CC}	V
		$I_{\text{O}} = 1.7 \text{ mA}$; $V_{\text{CC}} = 1.4 \text{ V}$	-	-	0.41	V
		$I_{\text{O}} = 1.9 \text{ mA}$; $V_{\text{CC}} = 1.65 \text{ V}$	-	-	0.39	V
		$I_{\text{O}} = 2.3 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	-	-	0.36	V
		$I_{\text{O}} = 3.1 \text{ mA}$; $V_{\text{CC}} = 2.3 \text{ V}$	-	-	0.50	V
		$I_{\text{O}} = 2.7 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	-	-	0.36	V
		$I_{\text{O}} = 4.0 \text{ mA}$; $V_{\text{CC}} = 3.0 \text{ V}$	-	-	0.50	V
I_{I}	input leakage current	$V_{\text{I}} = \text{GND}$ to 3.6 V ; $V_{\text{CC}} = 0 \text{ V}$ to 3.6 V	-	-	± 0.75	μA
I_{OFF}	power-off leakage current	V_{I} or $V_{\text{O}} = 0 \text{ V}$ to 3.6 V ; $V_{\text{CC}} = 0 \text{ V}$	-	-	± 0.75	μA
ΔI_{OFF}	additional power-off leakage current	V_{I} or $V_{\text{O}} = 0 \text{ V}$ to 3.6 V ; $V_{\text{CC}} = 0 \text{ V}$ to 0.2 V	-	-	± 0.75	μA
I_{CC}	supply current	$V_{\text{I}} = \text{GND}$ or V_{CC} ; $I_{\text{O}} = 0 \text{ A}$; $V_{\text{CC}} = 0.8 \text{ V}$ to 3.6 V	-	-	1.4	μA
ΔI_{CC}	additional supply current	$V_{\text{I}} = V_{\text{CC}} - 0.6 \text{ V}$; $I_{\text{O}} = 0 \text{ A}$; $V_{\text{CC}} = 3.3 \text{ V}$	-	-	75	μA

11. Dynamic characteristics

Table 8. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Max (125 °C)	
C_L = 5 pF									
t _{pd}	propagation delay	nA to nY; see Figure 8	[2]						
		V _{CC} = 0.8 V	-	16.0	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.4	5.0	10.3	2.1	11.4	12.6	ns
		V _{CC} = 1.4 V to 1.6 V	1.8	3.6	6.4	1.6	7.4	8.2	ns
		V _{CC} = 1.65 V to 1.95 V	1.5	2.9	5.0	1.4	5.9	6.5	ns
		V _{CC} = 2.3 V to 2.7 V	1.2	2.4	3.9	1.1	4.5	5.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.1	2.1	3.2	1.0	3.9	4.3	ns
C_L = 10 pF									
t _{pd}	propagation delay	nA to nY; see Figure 8	[2]						
		V _{CC} = 0.8 V	-	19.8	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	2.8	5.9	12.2	2.6	13.7	15.1	ns
		V _{CC} = 1.4 V to 1.6 V	2.3	4.2	7.5	2.1	8.7	9.6	ns
		V _{CC} = 1.65 V to 1.95 V	2.0	3.5	5.9	1.8	7.0	7.7	ns
		V _{CC} = 2.3 V to 2.7 V	1.7	2.9	4.6	1.5	5.4	6.0	ns
		V _{CC} = 3.0 V to 3.6 V	1.6	2.7	3.8	1.4	4.5	5.0	ns
C_L = 15 pF									
t _{pd}	propagation delay	nA to nY; see Figure 8	[2]						
		V _{CC} = 0.8 V	-	23.3	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	3.2	6.7	13.0	3.0	15.8	17.4	ns
		V _{CC} = 1.4 V to 1.6 V	2.6	4.7	8.6	2.4	10.0	11.0	ns
		V _{CC} = 1.65 V to 1.95 V	2.3	4.0	6.7	2.1	8.0	8.8	ns
		V _{CC} = 2.3 V to 2.7 V	2.1	3.3	5.1	1.8	6.1	6.8	ns
		V _{CC} = 3.0 V to 3.6 V	2.0	3.1	4.2	1.8	5.0	5.5	ns
C_L = 30 pF									
t _{pd}	propagation delay	nA to nY; see Figure 8	[2]						
		V _{CC} = 0.8 V	-	33.6	-	-	-	-	ns
		V _{CC} = 1.1 V to 1.3 V	4.4	8.9	16.0	4.0	19.0	20.9	ns
		V _{CC} = 1.4 V to 1.6 V	3.6	6.3	10.8	3.2	12.9	14.2	ns
		V _{CC} = 1.65 V to 1.95 V	3.2	5.3	9.0	2.9	10.5	11.6	ns
		V _{CC} = 2.3 V to 2.7 V	2.9	4.5	6.5	2.6	7.6	8.4	ns
		V _{CC} = 3.0 V to 3.6 V	2.9	4.2	5.4	2.6	6.2	6.9	ns

Table 8. Dynamic characteristics ...continued

Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +125 °C			Unit
			Min	Typ ^[1]	Max	Min	Max (85 °C)	Max (125 °C)	
$C_L = 5 \text{ pF, } 10 \text{ pF, } 15 \text{ pF and } 30 \text{ pF}$									
C_{PD}	power dissipation capacitance	$f_i = 1 \text{ MHz; } V_i = \text{GND to } V_{CC}$	[3][4]						
		$V_{CC} = 0.8 \text{ V}$	-	2.5	-	-	-	-	pF
		$V_{CC} = 1.1 \text{ V to } 1.3 \text{ V}$	-	2.7	-	-	-	-	pF
		$V_{CC} = 1.4 \text{ V to } 1.6 \text{ V}$	-	2.8	-	-	-	-	pF
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	-	3.0	-	-	-	-	pF
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	-	3.5	-	-	-	-	pF
		$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	-	4.0	-	-	-	-	pF

[1] All typical values are measured at nominal V_{CC} .[2] t_{pd} is the same as t_{PLH} and t_{PHL} .

[3] All specified values are the average typical values over all stated loads.

[4] C_{PD} is used to determine the dynamic power dissipation (P_D in μW). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; f_o = output frequency in MHz; C_L = load capacitance in pF; V_{CC} = supply voltage in V;

N = number of inputs switching;

 $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.

12. Waveforms

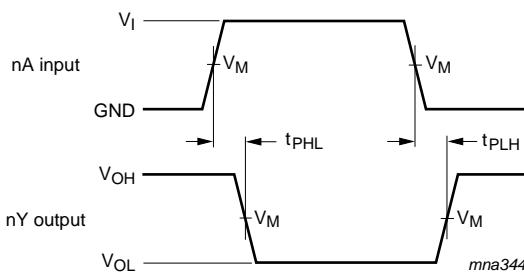
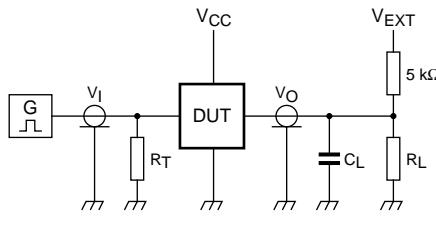
Measurement points are given in [Table 9](#).Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Fig 8. The data input (nA) to output (nY) propagation delays

Table 9. Measurement points

Supply voltage	Output	Input			
V_{CC} 0.8 V to 3.6 V	V_M 0.5 V_{CC}	V_M 0.5 V_{CC}	V_I V_{CC}	$t_r = t_f$ $\leq 3.0 \text{ ns}$	



001aac521

Test data is given in [Table 10](#).

Definitions for test circuit:

R_L = Load resistance.

C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_0 of the pulse generator.

V_{EXT} = External voltage for measuring switching times.

Fig 9. Test circuit for measuring switching times

Table 10. Test data

Supply voltage	Load	V_{EXT}			
V_{CC}	C_L	R_L ^[1]	t_{PLH}, t_{PHL}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
0.8 V to 3.6 V	5 pF, 10 pF, 15 pF, and 30 pF	5 kΩ or 1 MΩ	open	GND	2 V_{CC}

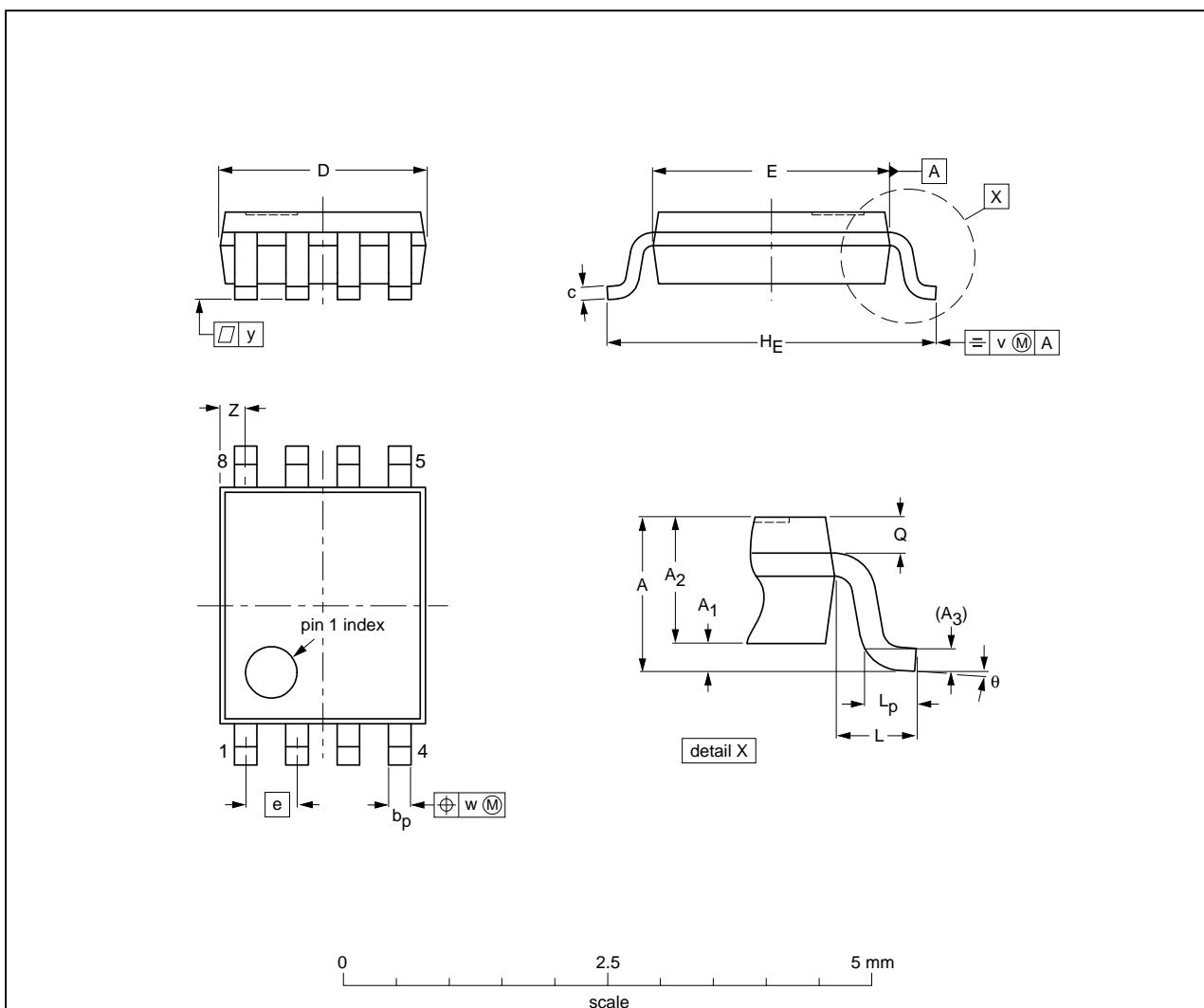
[1] For measuring enable and disable times, $R_L = 5 \text{ k}\Omega$.

For measuring propagation delays, setup and hold times, and pulse width, $R_L = 1 \text{ M}\Omega$.

13. Package outline

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1	0.15 0.00	0.85 0.60	0.12	0.27 0.17	0.23 0.08	2.1 1.9	2.4 2.2	0.5	3.2 3.0	0.4	0.40 0.15	0.21 0.19	0.2	0.13	0.1	0.4 0.1	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT765-1		MO-187				02-06-07

Fig 10. Package outline SOT765-1 (VSSOP8)

XSON8: plastic extremely thin small outline package; no leads; 8 terminals; body $1 \times 1.95 \times 0.5$ mm

SOT833-1

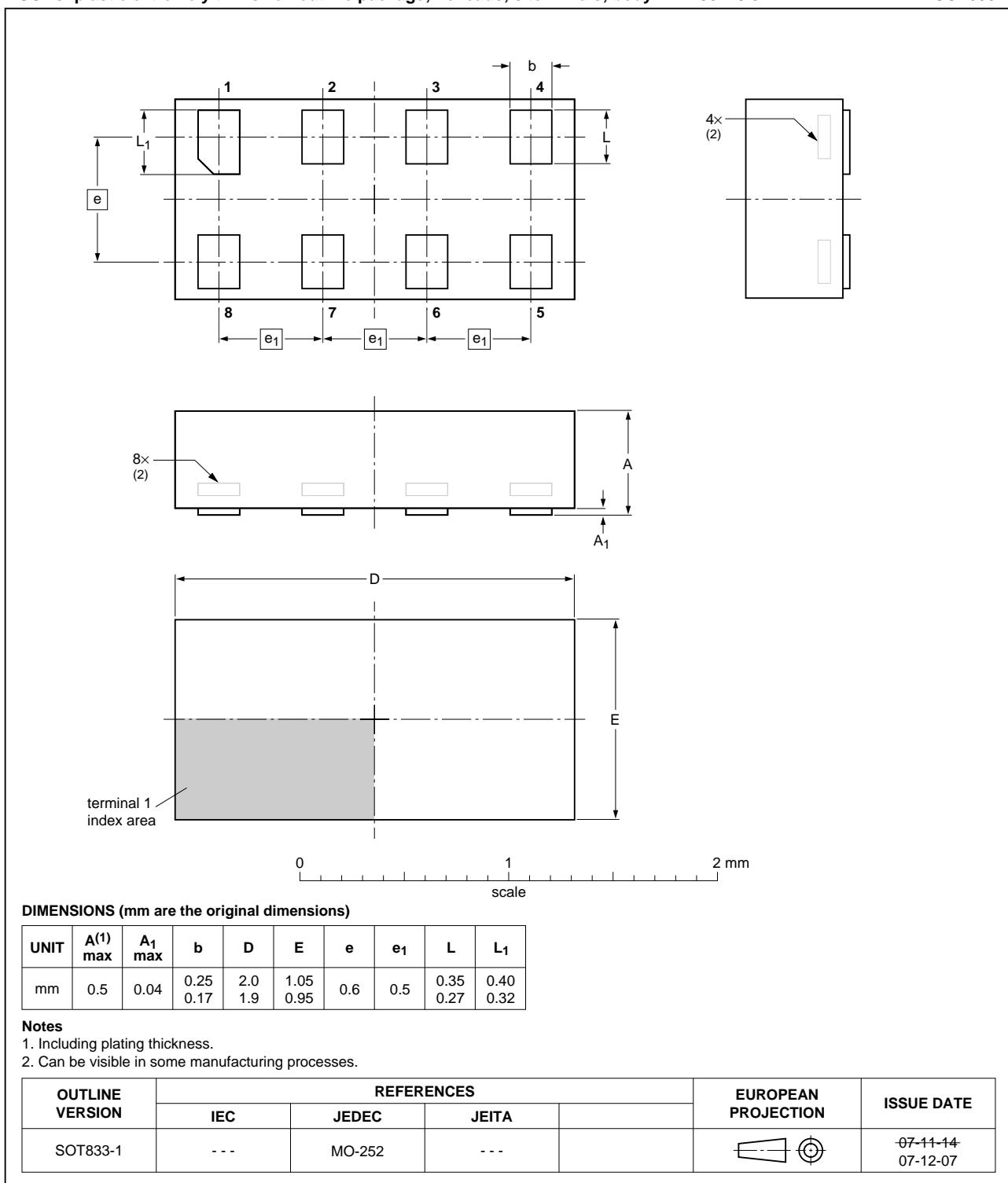


Fig 11. Package outline SOT833-1 (XSON8)

**XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.35 x 1 x 0.5 mm**

SOT1089

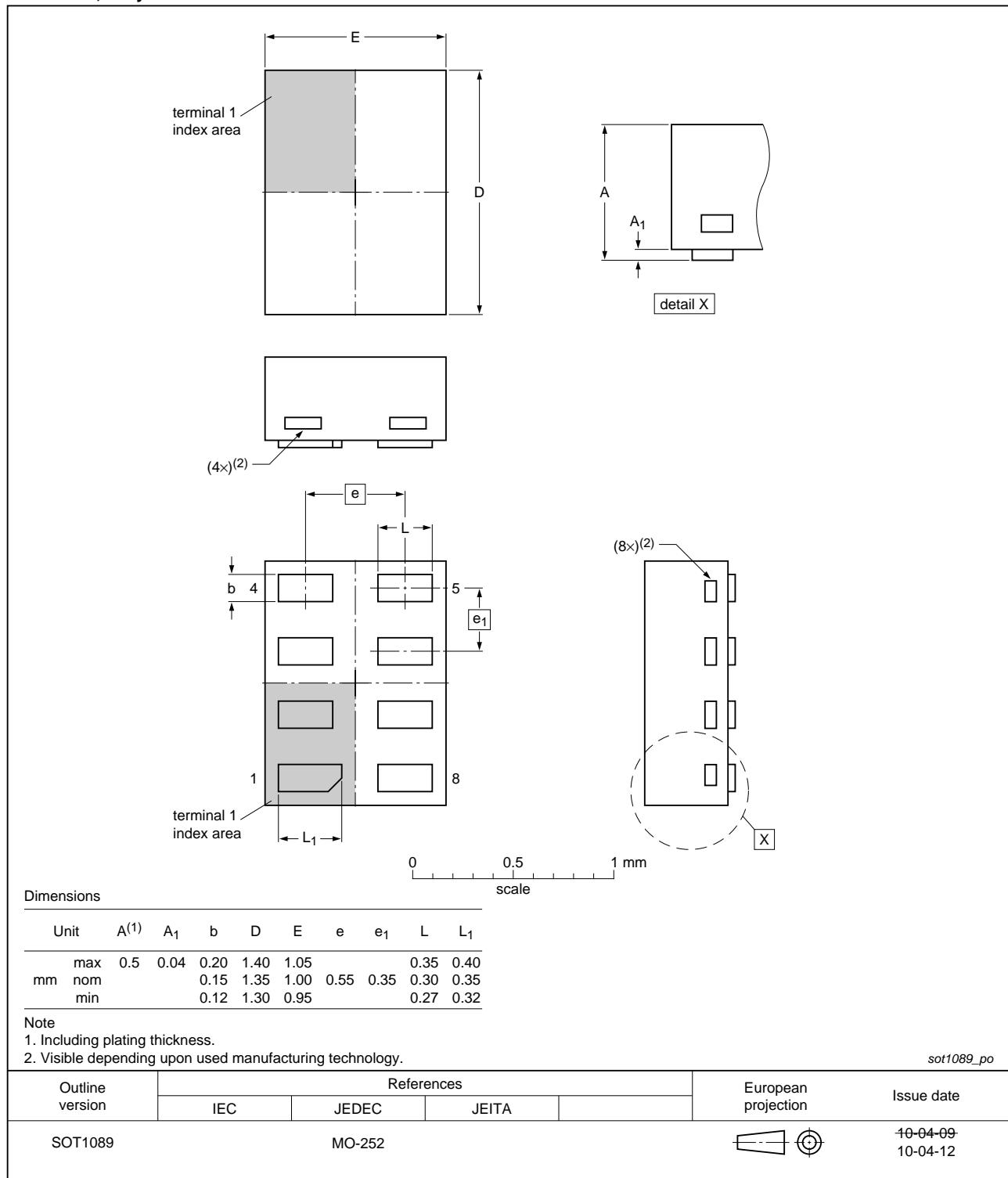


Fig 12. Package outline SOT1089 (XSON8)

XSON8: plastic extremely thin small outline package; no leads;
8 terminals; body 3 x 2 x 0.5 mm

SOT996-2

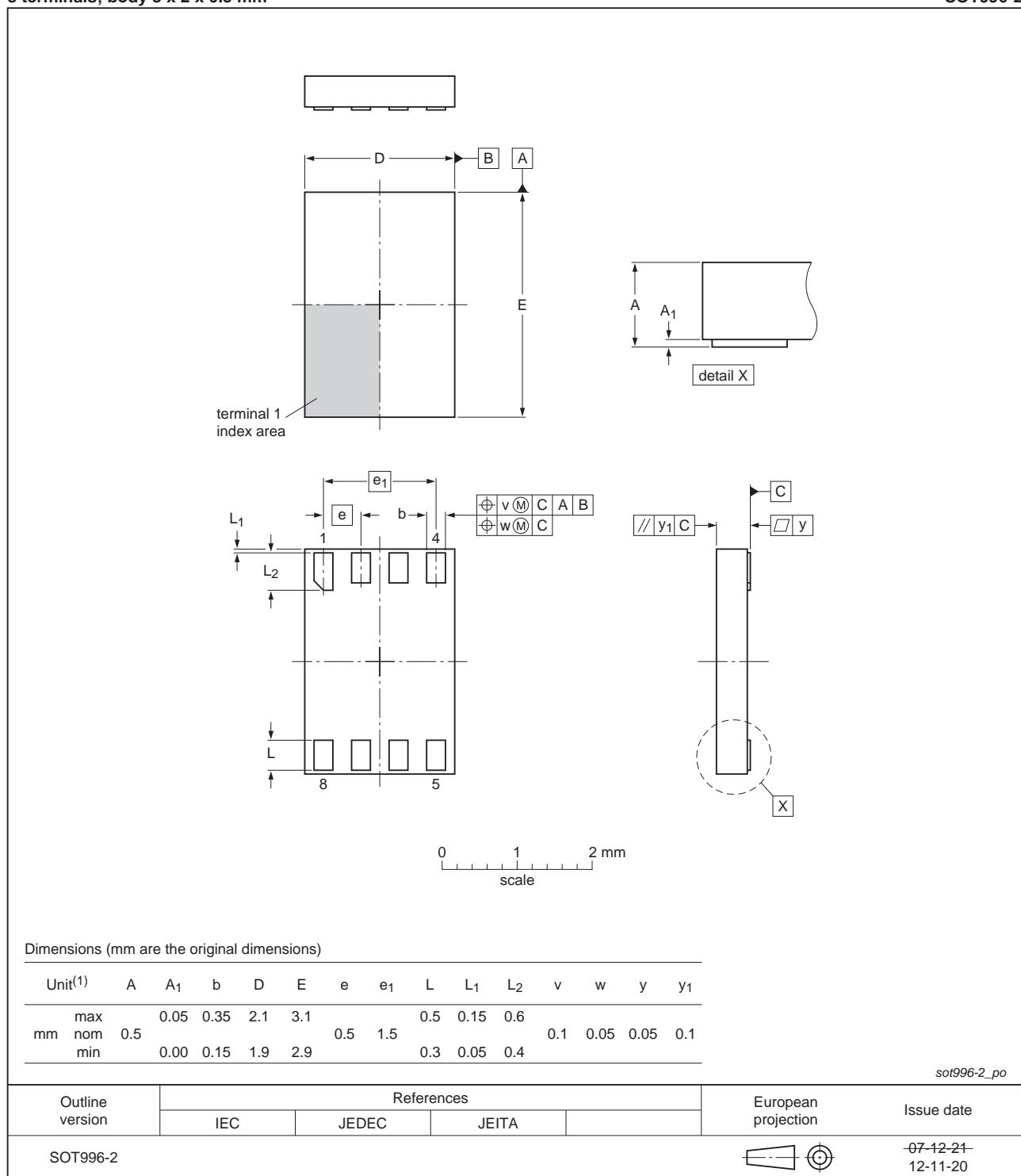


Fig 13. Package outline SOT996-2 (XSON8)

XQFN8: plastic, extremely thin quad flat package; no leads;
8 terminals; body 1.6 x 1.6 x 0.5 mm

SOT902-2

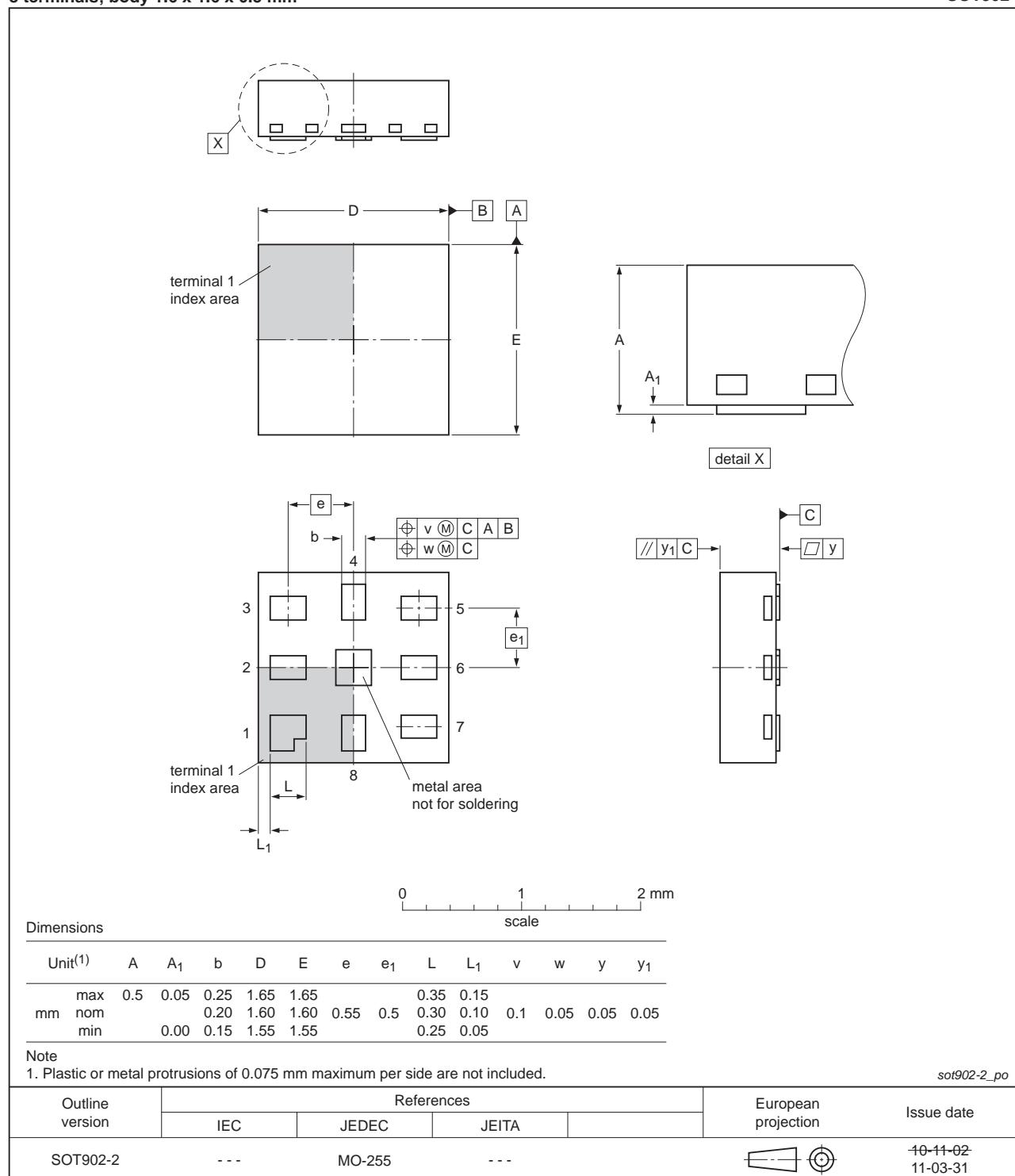


Fig 14. Package outline SOT902-2 (XQFN8)

**XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.2 x 1.0 x 0.35 mm**

SOT1116

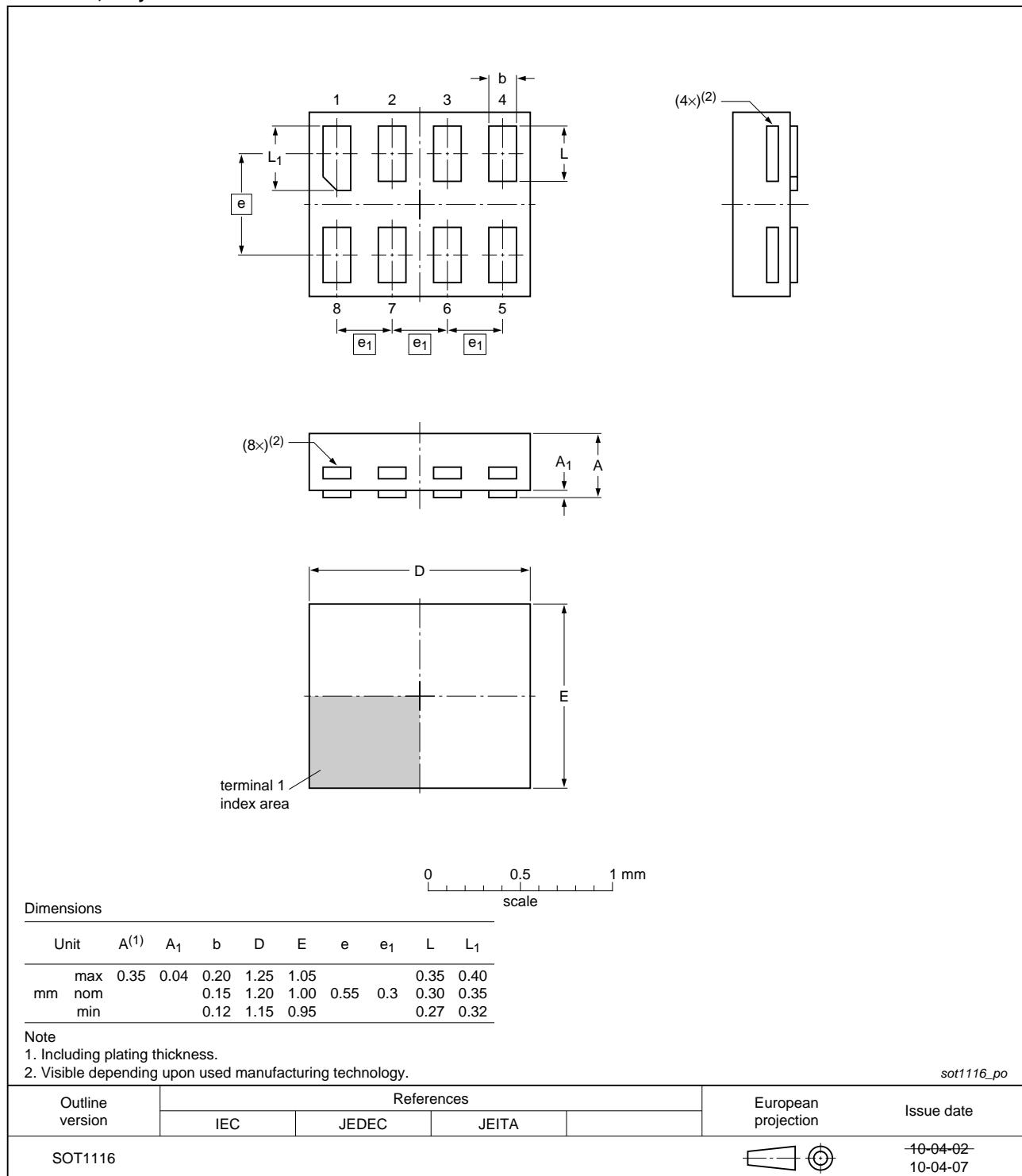


Fig 15. Package outline SOT1116 (XSON8)

**XSON8: extremely thin small outline package; no leads;
8 terminals; body 1.35 x 1.0 x 0.35 mm**

SOT1203

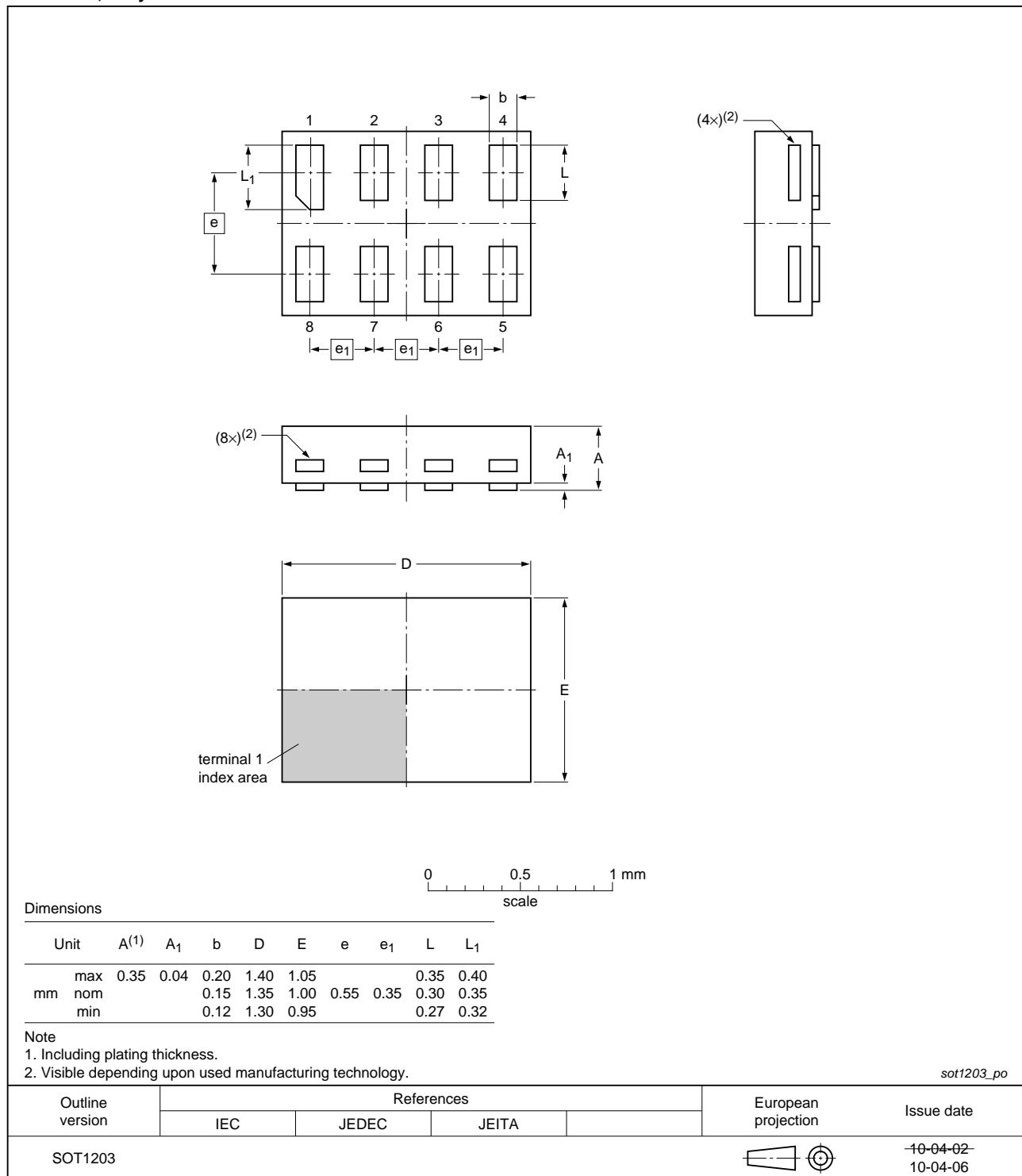


Fig 16. Package outline SOT1203 (XSON8)

14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AUP3G04 v.7	20130129	Product data sheet	-	74AUP3G04 v.6
Modifications:	<ul style="list-style-type: none"> For type number 74AUP3G04GD XSON8U has changed to XSON8. 			
74AUP3G04 v.6	20120614	Product data sheet	-	74AUP3G04 v.5
74AUP3G04 v.5	20111209	Product data sheet	-	74AUP3G04 v.4
74AUP3G04 v.4	20100730	Product data sheet	-	74AUP3G04 v.3
74AUP3G04 v.3	20091008	Product data sheet	-	74AUP3G04 v.2
74AUP3G04 v.2	20080313	Product data sheet	-	74AUP3G04 v.1
74AUP3G04 v.1	20070524	Product data sheet	-	-

16. Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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18. Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	2
4	Marking	2
5	Functional diagram	3
6	Pinning information	3
6.1	Pinning	3
6.2	Pin description	4
7	Functional description	4
8	Limiting values	5
9	Recommended operating conditions	5
10	Static characteristics	6
11	Dynamic characteristics	9
12	Waveforms	10
13	Package outline	12
14	Abbreviations	19
15	Revision history	19
16	Legal information	20
16.1	Data sheet status	20
16.2	Definitions	20
16.3	Disclaimers	20
16.4	Trademarks	21
17	Contact information	21
18	Contents	22

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